Low-Voltage CMOS Hex Inverter

With 5 V–Tolerant Inputs

The 74LVC04A is a high performance hex inverter operating from a 1.2 to 3.6 V supply. High impedance TTL compatible inputs significantly reduce current loading to input drivers while TTL compatible outputs offer improved switching noise performance. A V_I specification of 5.5 V allows 74LVC04A inputs to be safely driven from 5 V devices if V_{CC} is less than 5.0 V.

Current drive capability is 24 mA at the outputs.

Features

- Designed for 1.2 V to 3.6 V V_{CC} Operation
- 5.0 V Tolerant Inputs Interface Capability With 5.0 V TTL Logic
- 24 mA Output Sink and Source Capability
- Near Zero Static Supply Current (10 µA) Substantially Reduces System Power Requirements
- ESD Performance: Human Body Model >2000 V Machine Model >200 V
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

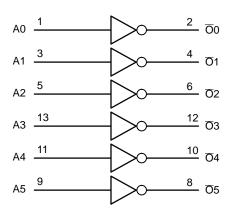


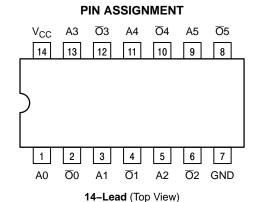
Figure 1. Logic Diagram



ON Semiconductor®

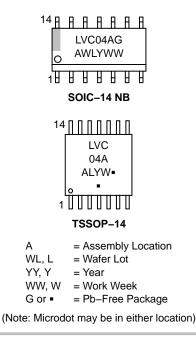
www.onsemi.com





14-Leau (Top view)

MARKING DIAGRAMS



ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

PIN NAMES

Pins	Function
An	Data Inputs
Ōn	Outputs

TRUTH TABLE

An	Ōn			
L H	H L			

MAXIMUM RATINGS

Symbol	Parameter	Value	Condition	Unit
V _{CC}	DC Supply Voltage	-0.5 to +6.5		V
VI	DC Input Voltage	$-0.5 \le V_{I} \le +6.5$		V
V _O	DC Output Voltage	$-0.5 \le V_O \le V_{CC} + 0.5$	Output in HIGH or LOW State (Note 1)	V
I _{IK}	DC Input Diode Current	-50	V _I < GND	mA
I _{OK}	DC Output Diode Current	-50	V _O < GND	mA
		+50	$V_{O} > V_{CC}$	mA
Ι _Ο	DC Output Source/Sink Current	±50		mA
I _{CC}	DC Supply Current Per Supply Pin	±100		mA
I _{GND}	DC Ground Current Per Ground Pin	±100		mA
T _{STG}	Storage Temperature Range	-65 to +150		°C
ΤL	Lead Temperature, 1 mm from Case for 10 Seconds	T _L = 260		°C
TJ	Junction Temperature Under Bias	T _J = 135		°C
θ_{JA}	Thermal Resistance (Note 2)	SOIC = 85 TSSOP = 100		°C/W
MSL	Moisture Sensitivity		Level 1	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. I_O absolute maximum rating must be observed.

2. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Тур	Max	Units
V _{CC}	Supply Voltage Operating Functional	1.65 1.2		3.6 3.6	V
VI	Input Voltage	0		5.5	V
V _O	Output Voltage HIGH or LOW State 3–State	0 0		V _{CC} 5.5	V
I _{OH}	$ HIGH Level Output Current \\ V_{CC} = 3.0 V - 3.6 V \\ V_{CC} = 2.7 V - 3.0 V $			-24 -12	mA
I _{OL}	$ LOW Level Output Current \\ V_{CC} = 3.0 V - 3.6 V \\ V_{CC} = 2.7 V - 3.0 V $			24 12	mA
T _A	Operating Free–Air Temperature	-40		+125	°C
Δt/ΔV	Input Transition Rise or Fall Rate $V_{CC} = 1.65 \text{ V to } 2.7 \text{ V}$ $V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	0 0		20 10	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

			−40°C to +85°C			–40°C to +125°C			
Symbol	Parameter	Conditions	Min	Typ (Note 3)	Max	Typ Min (Note 3)		Max	Unit
VIH	HIGH-level input	V _{CC} = 1.2 V	1.08	-	Ι	1.08	-	-	V
	voltage	$V_{CC} = 1.65 \text{ V} \text{ to } 1.95 \text{ V}$	0.65 x V _{CC}	-	-	0.65 x V _{CC}	-	-	
		V_{CC} = 2.3 V to 2.7 V	1.7	-	-	1.7	-	_	
		V_{CC} = 2.7 V to 3.6 V	2.0	-	-	2.0	-	_	
V _{IL}	LOW-level input	V _{CC} = 1.2 V	-	-	0.12	-	-	0.12	V
	voltage	V _{CC} = 1.65 V to 1.95 V	-	-	0.35 x V _{CC}	-	-	0.35 x V _{CC}	
		V_{CC} = 2.3 V to 2.7 V	-	-	0.7	-	-	0.7	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	-	-	0.8	-	-	0.8	
V _{OH}	HIGH-level output	$V_{I} = V_{IH}$ (or V _{IL}						V
	voltage	$I_{O} = -100 \ \mu\text{A};$ $V_{CC} = 1.65 \ \text{V} \text{ to } 3.6 \ \text{V}$	V _{CC} – 0.2	_	_	V _{CC} – 0.3	-	_	
		$I_{O} = -4 \text{ mA}; V_{CC} = 1.65 \text{ V}$	1.2	-	-	1.05	-	-	
		$I_{O} = -8 \text{ mA}; V_{CC} = 2.3 \text{ V}$	1.8	-	-	1.65	-	-	
		$I_{O} = -12 \text{ mA}; V_{CC} = 2.7 \text{ V}$	2.2	-	-	2.05	-	-	
		$I_{O} = -18 \text{ mA}; V_{CC} = 3.0 \text{ V}$	2.4	-	-	2.25	-	-	
		$I_{O} = -24$ mA; $V_{CC} = 3.0$ V	2.2	-	-	2.0	-	-	
VOL	LOW-level output	$V_{I} = V_{IH}$ ($V_{I} = V_{IH} \text{ or } V_{IL}$						V
	voltage	$I_O = 100 \ \mu\text{A};$ $V_{CC} = 1.65 \ \text{V} \text{ to } 3.6 \ \text{V}$	-	-	0.2	-	-	0.3	
		I _O = 4 mA; V _{CC} = 1.65 V	-	-	0.45	-	-	0.65	
		I _O = 8 mA; V _{CC} = 2.3 V	-	-	0.6	-	-	0.8	
		$I_0 = 12 \text{ mA}; V_{CC} = 2.7 \text{ V}$	-	-	0.4	-	-	0.6	
		$I_{O} = -24$ mA; $V_{CC} = 3.0$ V	-	-	0.55	-	-	0.8	
lı	Input leakage current	$V_{\rm I}$ = 5.5V or GND $V_{\rm CC}$ = 3.6 V	-	±0.1	±5	-	±0.1	±20	μA
I _{OFF}	Power-off leakage current	V_{I} or V_{O} = 5.5 V; V_{CC} = 0.0 V	-	±0.1	±10	-	±0.1	±20	μA
I _{CC}	Supply current	$V_{I} = V_{CC} \text{ or } \text{GND; } I_{O} = 0 \text{ A;}$ $V_{CC} = 3.6 \text{ V}$	Ι	0.1	10	-	0.1	40	μA
ΔI_{CC}	Additional supply current	per input pin; $V_I = V_{CC} - 0.6 \text{ V}; I_O = 0 \text{ A};$ $V_{CC} = 2.7 \text{ V} \text{ to } 3.6 \text{ V}$	-	5	500	_	5	5000	μΑ

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 3. All typical values are measured at $T_A = 25^{\circ}C$ and $V_{CC} = 3.3$ V, unless stated otherwise.

AC ELECTRICAL CHARACTERISTICS (t_R = t_F = 2.5 ns)

			–40°C to +85°C		–40°C to +125°C				
Symbol	Parameter	Conditions	Min	Typ ¹	Max	Min	Typ ¹	Max	Unit
t _{pd}	Propagation Delay (Note 5)	V _{CC} = 1.2 V	-	14.0	-	-	-	-	ns
		V_{CC} = 1.65 V to 1.95 V	0.5	3.7	8.8	0.5	-	10.2	ns
		V_{CC} = 2.3 V to 2.7 V	0.5	2.2	5.0	0.5	-	5.8	
		$V_{CC} = 2.7 V$	0.5	2.1	5.5	0.5	-	7.0	
		V_{CC} = 3.0 V to 3.6 V	0.5	2.0	4.5	0.5	1	6.0	
t _{sk(0)}	Output Skew Time (Note 6)	V_{CC} = 3.0 V to 3.6 V	-	-	1.0	-	-	1.5	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Typical values are measured at $TA = 25^{\circ}C$ and Vcc = 3.3 V, unless stated otherwise.

 t_{pd} is the same as t_{PLL} and t_{PLL}.
 Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (toshL) or LOW-to-HIGH (tosLH); parameter guaranteed by design.

DYNAMIC SWITCHING CHARACTERISTICS

			T _A = +25°C			
Symbol	Characteristic	Condition	Min	Тур	Мах	Unit
V _{OLP}	Dynamic LOW Peak Voltage (Note 7)			0.8 0.6		V
V _{OLV}	Dynamic LOW Valley Voltage (Note 7)			-0.8 -0.6		V

7. Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

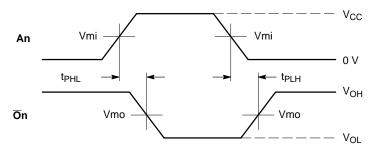
CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Unit	
CIN	Input Capacitance	$V_{CC} = 3.3 \text{ V}, \text{ V}_{I} = 0 \text{ V or } \text{V}_{CC}$	4.0	pF	
COUT	Output Capacitance	V_{CC} = 3.3 V, V_{I} = 0 V or V_{CC}	5.0	pF	
C_{PD}	Power Dissipation Capacitance	Per input; V _I = GND or V _{CC}			
	(Note 8)	V _{CC} = 1.65 V to 1.95 V	3.9		
		V_{CC} = 2.3 V to 2.7 V	7.1		
		V _{CC} = 3.0 V to 3.6 V	9.9		

8. C_{PD} is used to determine the dynamic power dissipation (P_D in μ W). P_D = C_{PD} x V_{CC}² x fi x N + Σ (C_L x V_{CC}² x fo) where: fi = input frequency in MHz; fo = output frequency in MHz C_L = output load capacitance in pF V_{CC} = supply voltage in Volts

N = number of outputs switching

 $\Sigma(C_L \times V_{CC}^2 \times fo) = \text{sum of the outputs.}$

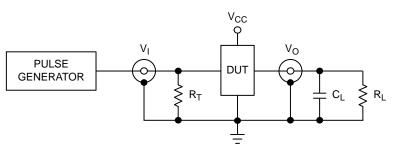


WAVEFORM 1 – PROPAGATION DELAYS

 t_{R} = t_{F} = 2.5 ns, 10% to 90%; f = 1 MHz; t_{W} = 500 ns

	Vcc					
Symbol	3.3 V <u>+</u> 0.3 V	2.7 V	V _{CC} < 2.7 V			
Vmi	1.5 V	1.5 V	Vcc/2			
Vmo	1.5 V	1.5 V	Vcc/2			

Figure 2. AC Waveforms



 C_L includes jig and probe capacitance R_T = Z_{OUT} of pulse generator (typically 50 $\Omega)$

Supply Voltage	Input		Lo	ad
V _{CC} (V)	VI	t _r , t _f	CL	RL
1.2	V _{CC}	≤ 2 ns	30 pF	1 kΩ
1.65 – 1.95	V _{CC}	≤ 2 ns	30 pF	1 kΩ
2.3 – 2.7	V _{CC}	≤ 2 ns	30 pF	500 Ω
2.7	2.7 V	\leq 2.5 ns	50 pF	500 Ω
3 – 3.6	2.7 V	\leq 2.5 ns	50 pF	500 Ω

Figure 3. Test Circuit

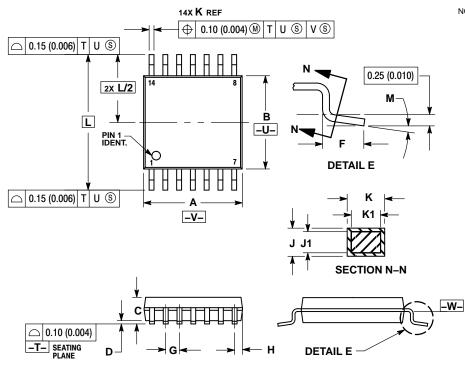
ORDERING INFORMATION

Device	Package	Shipping [†]
74LVC04ADR2G	SOIC-14 NB (Pb-Free)	2500 / Tape & Reel
74LVC04ADTR2G	TSSOP-14 (Pb-Free)	2500 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

TSSOP-14 CASE 948G **ISSUE B**



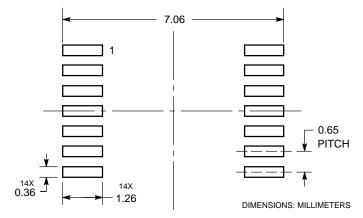
NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
 TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
- REFERENCE ONLY. 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-. 7

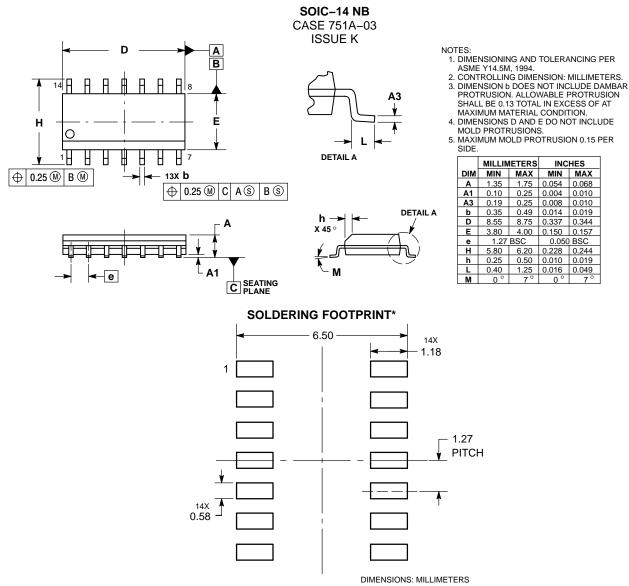
	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	4.90	5.10	0.193	0.200
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65	BSC	0.026 BSC	
Н	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
κ	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
М	0 °	8 °	0 °	8 °

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and the intervent and the intervent of the pattern of the patter

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303–675–2175 or 800–344–3860 Toll Free USA/Canada Fax: 303–675–2176 or 800–344–3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800–282–9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support:

Phone: 421 33 790 2910 Japan Customer Focus Center Phone: 81–3–5817–1050 ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative